

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A3			ADD SOME DETAILS	04/29'20	Larry

ORDERING INFORMATION

SMPI - S04 (XX T)

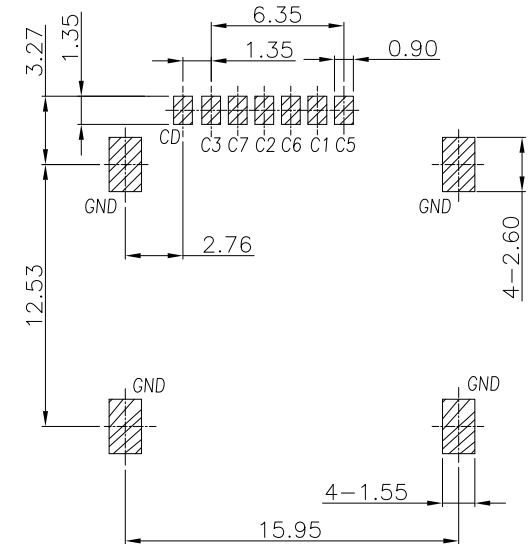
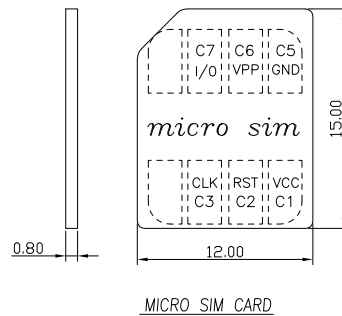
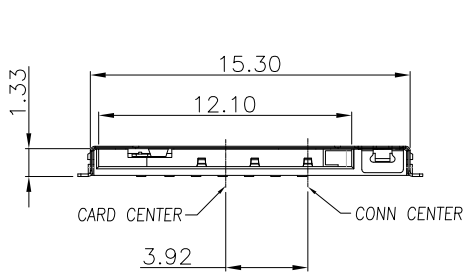
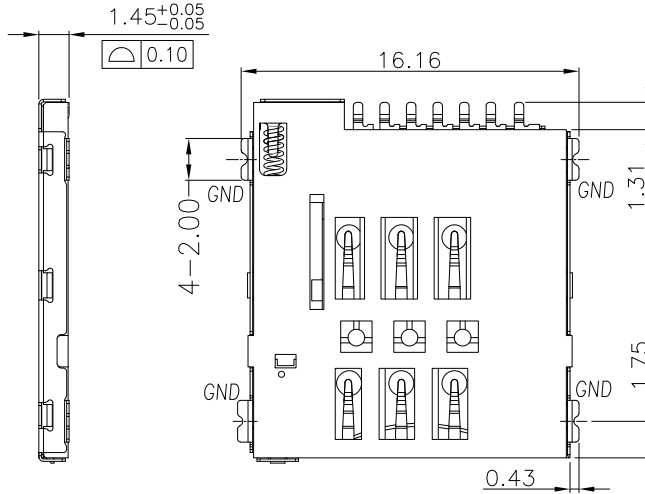
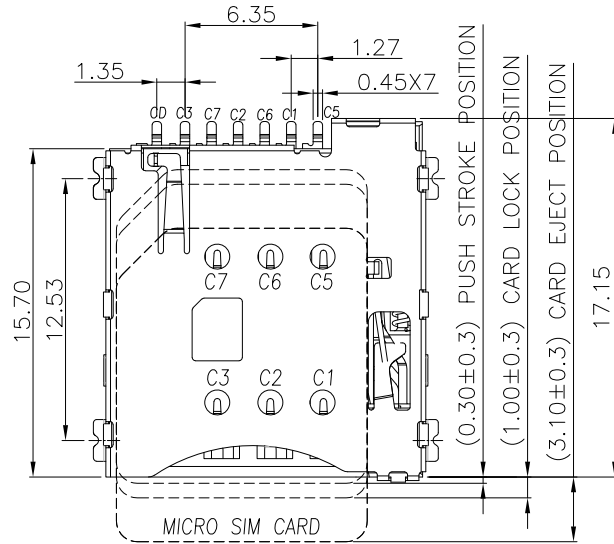
- ① **PRODUCT SERIES:**
Micro-SIM CARD SOCKET
PUSH-PUSH TYPE.
- ② **ITEM NO.:**
6+1PIN, 1.45mm Height.

CUSTOMER DRAWING

RoHS Compliant

③ **GOLD PLATING:**

- 01: G/F.
- 05: 5u".
- 10: 10u".
- 15: 15u".
- 30: 30u".



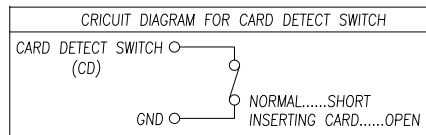
▨ SMT SOLDER AREA
THERE SHOULD NOT BE ANY CIRCUITRIES
IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

NOTES:

- 1) MATERIAL:
HOUSING: HI-TEMP, LCP, UL 94V-0.
CONTACT: COPPER ALLOY
SHELL: STAINLESS STEEL
- 2) FINISH:
CONTACT: GOLD OVER NICKEL ON CONTACT AREA;
GOLD FLASH PLATED ON SOLDER TAILS.
SHELL: GOLD FLASH PLATED ON SOLDER TAILS.

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



DIM	TOL
x.x	±0.30
x.xx	±0.20
x.xxx	±0.10

SUNFUN		SUNFUN TECHNOLOGY LTD			
DRAW NO.	SMPI-S04(A3)	DATE	MATERIAL: SEE NOTES	DRAW NAME:	
DESIGN:	Larry	04/29'20	FINISH: SEE NOTES	Micro-SIM Card Socket Push-Push Type, 6+1Pin 1.45mm Height	
CHECK:	Larry	04/29'20	FILE: SMPI-S04(A3)	MODEL: MICRO-SIM PP CONN	
REVIEW:	Ziv	04/29'20	P/N: SMPI-S04(XXT)	UNIT:	SHEET:
APPROVED	Ziv	04/29'20	REV. A3	mm	1/1
			SCALE		